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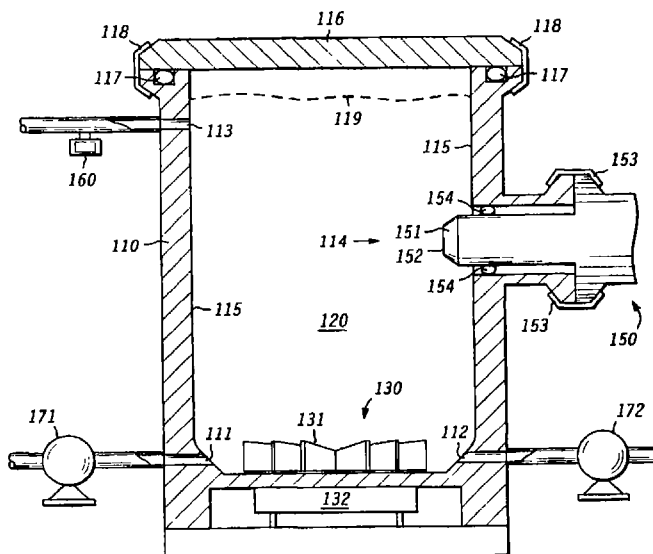
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4) Title: METHOD OF MANUFACTURING A SEMICONDUCTOR COMPONENT AND CHEMICAL-MECHANICAL POL-
ISHING SYSTEM THEREFOR



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(57) Abstract: A method of manufacturing a semiconductor component includes forming a first layer over a semiconductor sub-
strate, providing a mixture comprised of a first component and a second component, optically detecting a concentration of the first
component in the mixture, and applying the mixture to the first layer. A chemical-mechanical polishing (CMP) system (100) for use
in the method includes a vessel (110) having a first input port (111), a CMP slurry output port (113), and a CMP slurry sensing port
(114). The CMP system also includes a refractometer (150) adjacent to the CMP slurry sensing port.

WO 01/89767 A2



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